

SOT1050

plastic ultra thin small outline package; no leads; 6 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	USON6
Package type industry code	USON6
Package style descriptive code	USON (ultra thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	3-6-2008

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.4	-	1.5	1.6	mm
E	package width		2	-	2.1	2.2	mm
A	seated height		[tbd]	-	[tbd]	0.55	mm
e	nominal pitch		-	-	0.4	-	mm
n ₂	actual quantity of termination		-	-	6	-	



2. Package outline

USON6: plastic ultra thin small outline package; no leads;
6 terminals; body 1.5 x 2.1 x 0.55 mm

SOT1050

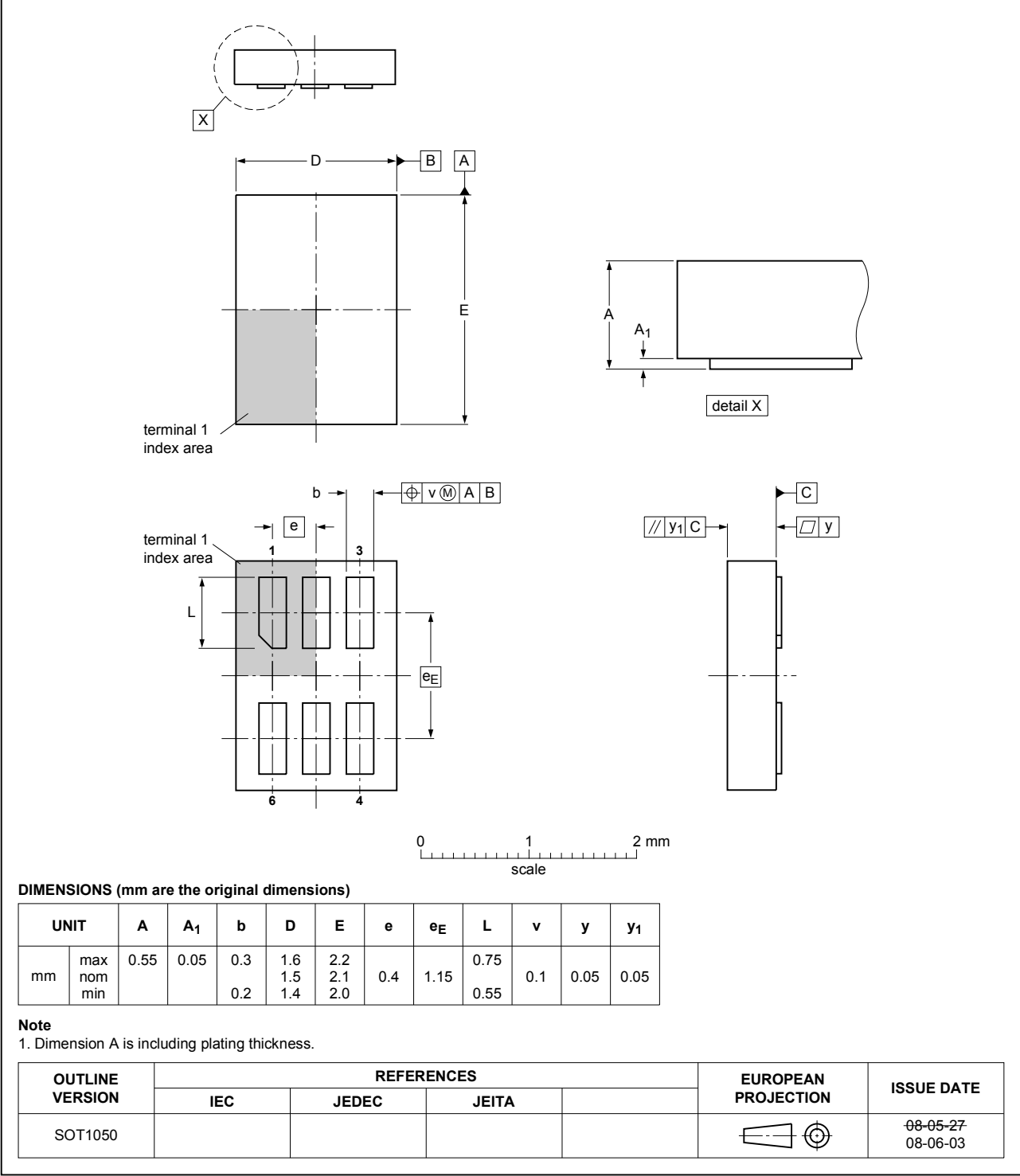


Fig. 1. Package outline USON6 (SOT1050)

3. Legal information

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4. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Legal information..... 3

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